



IEEE 3DIC 2024



The 13th International 3D Systems Integration Conference
September 25th – 27th, 2024, Sendai, Japan

1st Call for Papers

The IEEE International 3D Systems Integration Conference (3DIC) will be held at the Hotel Metropolitan Sendai and Sendai Kokusai Hotel in Sendai, Japan, September 25th-27th, 2024. The deadline for abstract submission is ***June 14, 2024***. Abstracts should be 1 page text (500 words) and 1 page figures.

3DIC 2024 will cover all **3D system integration** topics, including 3D/Chiplet process technology, materials, equipment, circuits technology, design methodology, and applications. The conference invites authors and attendees to submit and interact with researchers from all around the world. Papers are solicited in subject topics, including, but not limited to, the following:

3D/Chiplet Integration Technology: Through-Si Vias (TSV), Hybrid bonding, Wafer thinning, Wafer/Chip alignment, WtW/WtC/CtC bonding, Wafer dicing, Interposer (Si/Glass/Organic), Optical interconnect, FOWLP, Monolithic 3D integration, Heterogeneous integration, and Chiplet technology

3D/Chiplet Circuits Technology: SoC, 3D NAND, HBM, CPU/GPU, DSP, FPGA, ASIC, RF and mm-wave, Analog circuits, Biomedical circuits, and Chiplet design

3D/Chiplet Applications: Artificial Intelligence, Machine Learning, Deep Learning, Imaging, IoT, Memory, Processors, Communications, Networking, Wireless, Sensors, Biomedical

3D/Chiplet Design and Test Methodology: CAD, Synthesis, Design flows, Signal and power integrity analysis and design in 3D/Chiplet, Thermal design and analysis, Test and design for test, Mechanical stress and reliability design and analysis

2024 Conference Co-Chairs:

T. Tanaka (Tohoku Univ), P. Franzon (NCSU)

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Conference website: www.3dic-conf.org

